

SMD INDUCTORS

MODEL NO. : SMI-60 SERIES

FEATURES:

- * SUPERIOR QUALITY FROM AN AUTOMATED PRODUCTION LINE.
- * PICK AND PLACE COMPATIBLE.
- * TAPE AND REEL PACKING.

APPLICATION :

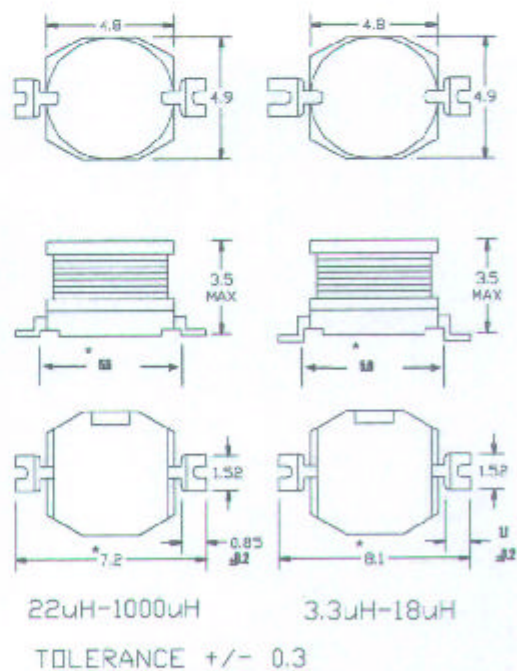
- * NOTEBOOK COMPUTERS.
- * DC-DC CONVERTORS.
- * DC-AC INVERTERS.
- * SIGNAL CONDITIONING
- * CELLULAR TELEPHONES
- * FILTERING.
- * HYBRIDS
- * PAGERS.
- * PDA.



ELECTRICAL SPECIFICATION:

MODEL NO.	L (μ H)	DCR MAX (OHMS)	RATED DC CURRENT (mA)
SMI-60-3R3	3.3	0.065	1000
SMI-60-4R7	4.7	0.075	1000
SMI-60-6R8	6.8	0.12	750
SMI-60-100	10	0.16	600
SMI-60-120	12	0.21	500
SMI-60-150	15	0.23	500
SMI-60-180	18	0.30	450
SMI-60-220	22	0.35	400
SMI-60-270	27	0.50	300
SMI-60-330	33	0.60	250
SMI-60-390	39	0.63	250
SMI-60-470	47	0.74	250
SMI-60-560	56	0.95	200
SMI-60-680	68	1.0	200
SMI-60-820	82	1.5	200
SMI-60-101	100	1.5	180
SMI-60-121	120	1.8	180
SMI-60-151	150	2.2	150
SMI-60-181	180	2.3	150
SMI-60-221	220	3.3	130
SMI-60-271	270	3.8	120
SMI-60-331	330	4.8	100
SMI-60-471	470	8.3	50
SMI-60-681	680	10.5	50
SMI-60-821	820	11.5	50
SMI-60-102	1000	15	50

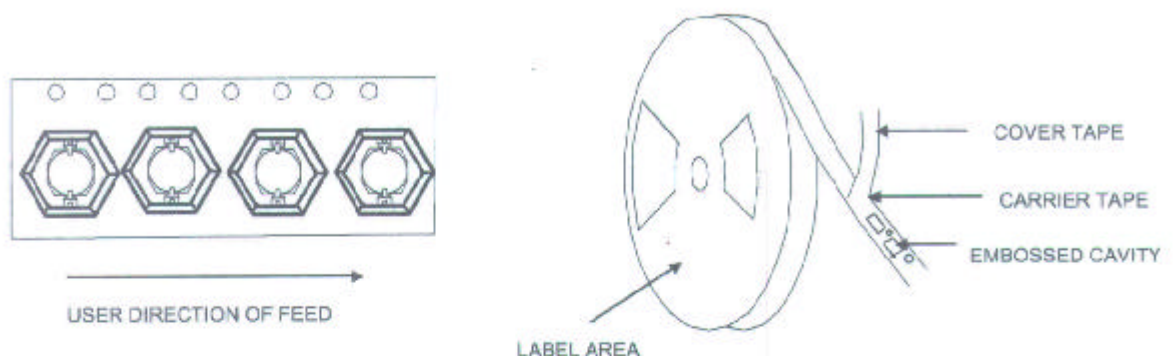
PHYSICAL DIMENSION : (UNIT:mm)



NOTE(1): TEST FREQUENCY: 100KHz, 1VRMS.
NOTE(2): 3.3uH-6.8uH +20%, 10uH-1000uH $\pm$ 10%.

PACKING

Tape and Reel Orientation



NOTE : Top view shown with cover tape removed.

TAPE	WIDTH	REEL	WIDTH	COMPONENT	PITCH	UNITS	PER	REEL
	16mm		22.4mm		8mm			2500

TAPE SPECIFICATIONS:

Carrier Tape Type : Conductive.

Cover Tape Type : Antistatic.

Cover Tape Adhesion to Carrier : 10 - 70 grams.

REEL SPECIFICATIONS:

Diameter (flange) : 13" (330.2mm)

STANDARDS : All embossed carrier tape packaging will be accomplished in compliance with latest revision of EIA-481 "Taping of surface Mount Components for Automatic Placement".

ENVIRONMENTAL PERFORMANCE

ITEM	TEST	CONDITION
1	Thermal Shock	One cycle shall consist of: (1) 30minutes at temperature -30°C (2) 15 seconds maximum at room ambient. (3) 30 minutes at temperature +85°C (4) 15 seconds maximum at room ambient. Subject samples to 10 cycles. Test per applicable devices specification after a 4 hours stabilization at room ambient.
2	Vibration	Inductance deviation within $\pm 3.0\%$ after vibration for 1 hour. In each of three orientations at sweep vibration (10~50~10Hz) with 1.5mm P-P amplitude.
3	Solderability	Solder pot at $230^{\circ}\text{C} \pm 5^{\circ}\text{C}$, with kester 1544 solder flux. Dip parts into solder pot containing 63/37 molten alloy for 5 second $\pm$ 1 second. Wetting must occur on a minimum of 90% of the terminations.
4	Operating Temperature	-25°C ~ +80°C (coil contain heat)
5	Humidity	Inductance deviation within $\pm 5.0\%$ After 96 hour in 90~95% relative humidity at $40 \pm 2^{\circ}\text{C}$ and 1 hour drying under normal condition.
6	Mechanical Shock	One-half sine pulse (8700 g's for 0.3 milliseconds) in each direction along 3 mutually perpendicular axes in each direction (total of 6 shocks).